STARPOWER

SEMICONDUCTOR

MOSFET

MD200HFR120C2S

1200V/200A 2 in one-package

General Description

STARPOWER MOSFET Power Module provides very low $R_{DS(on)}$ as well as optimized intrinsic diode. It's designed for the applications such SMPS and DC drives.

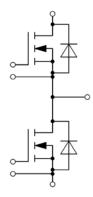
Features

- SiC power MOSFET
- Low R_{DS(on)}
- Optimized intrinsic reverse diode
- Chip sintering technology
- Low inductance case avoid oscillations
- Isolated copper baseplate using AlN DBC technology

Typical Applications

- Main and auxiliary AC drives of electric vehicles
- DC servo and robot drives
- Battery vehicles
- UPS equipment
- Plasma cutting

Equivalent Circuit Schematic



Absolute Maximum Ratings

MOSFET

Symbol	Description	Value	Unit	
$V_{ m DSS}$	Drain-Source Voltage	1200	V	
V_{GSS}	Gate-Source Voltage	±20	V	
T	Drain Current @ T _C =25°C	299	Α	
\mathbf{I}_{D}	$@ T_{C} = 105^{\circ}C$	200	А	
I_{DM}	Pulsed Drain Current	822	A	

Inverse Diode

Symbol	Description	Value	Unit
I_{S}	Source Current	200	Α
I_{SM}	Pulsed Source Current	822	Α

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	°C
T_{jop}	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature Range	-40 to +125	°C
$V_{\rm ISO}$	Isolation Voltage RMS,f=50Hz,t=1min	4000	V

MOSFET Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	Static Drain-Source	$I_D=120A, V_{GS}=18V,$ $T_j=25^{\circ}C$		6.7	8.7	mΩ
	On-Resistance	I _D =120A,V _{GS} =18V, T _i =125°C		10.0		
$V_{\text{GS(th)}}$	Gate-Source Threshold Voltage	I_{D} =60mA, V_{DS} = V_{GS} , T_{j} =25°C	2.7		5.6	V
g_{fs}	Forward Transconductance	V _{DS} =10V,I _D =120A		49.8		S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=V_{DSS}, V_{GS}=0V,$ $T_j=25^{\circ}C$			60	μΑ
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=V_{GSS}, V_{DS}=0V,$ $T_j=25^{\circ}C$			0.6	μΑ
C_{iss}	Input Capacitance			8.0		nF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 800V,$		0.46		nF
C_{rss}	Reverse Transfer Capacitance	f=1MHz		0.16		nF
Q_{g}	Total Gate Charge			642		nC
Q_{gs}	Gate-Source Charge	$I_D=120A, V_{DS}=600V,$		132		nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=18V$		246		nC
t _{d(on)}	Turn-On Delay Time	V _400VI _109A		21		ns
t _r	Rise Time	$V_{DS}=400V, I_D=108A,$		39		ns
$t_{d(off)}$	Turn-Off Delay Time	$R_G=0\Omega, V_{GS}=18V,$ $T_j=25^{\circ}C$		49		ns
t_{f}	Fall Time			24		ns
Eon	Turn-On Switching Loss	V _{DS} =600V,I _D =120A,		1.70		mJ
$E_{ m off}$	Turn-Off Switching Loss	$R_G=0\Omega, V_{GS}=18V,$ $T_j=25^{\circ}C$		0.71		mJ

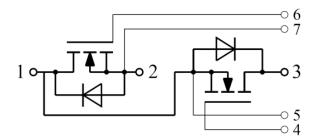
Inverse Diode Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V_{SD}	Diode Forward Voltage	$I_{S}=120A, V_{GS}=0V, T_{j}=25^{\circ}C$		3.2		V
t _{rr}	Diode Reverse Recovery Time	V_R =600V, I_S =120A, -di/dt=6600A/ μ s, T_j =25°C		25		ns
Q_{r}	Diode Reverse Recovery Charge			0.69		μС
I_{RM}	Peak Reverse Recovery Current			54		A

Module Characteristics $T_C=25^{\circ}C$ unless otherwise noted

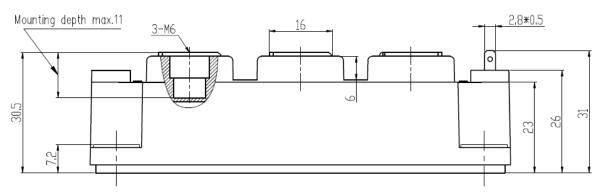
Symbol	Parameter	Min.	Тур.	Max.	Unit
R_{thJC}	Junction-to-Case(Mosfet)			0.122	K/W
R_{thCH}	Case-to-Heatsink (Mosfet)		0.020		K/W
	Case-to-Heatsink (per Module)		0.010		IX/ W
M	Terminal Connection Torque, Screw M6	2.5		5.0	N.m
	Mounting Torque, Screw M6	3.0		5.0	IN.III
G	Weight of Module		300		g

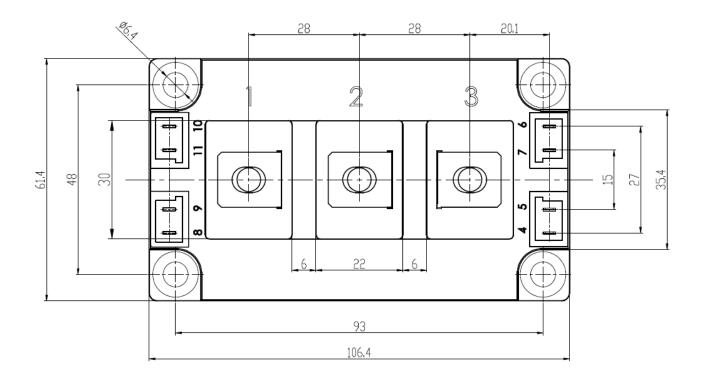
Circuit Schematic



Package Dimensions

Dimensions in Millimeters





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